

Material Composition Specification

SOT-363 Case

Pb (lead)-free plating**



Device average mass **5.9 mg**

Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	3.44%	0.20	Si	7440-21-3	3.44%	0.20	34,390
bond wire	gold	0.63%	0.04	Au	7440-57-5	0.63%	0.04	6,330
leadframe	alloy 42 w/ silver plating	32.96%	1.94	Fe	7439-89-6	19.08%	1.13	190,780
				Ni	7440-02-0	13.26%	0.78	132,580
				Ag	7440-22-4	0.62%	0.04	6,200
encapsulation*	EMC	58.28%	3.44	silica	7631-86-9	42.03%	2.48	420,330
				epoxy resin	Proprietary	14.64%	0.86	146,440
				Sb ₂ O ₃	1309-64-4	1.17%	0.07	11,690
				TBBA	79-94-7	0.29%	0.02	2,920
				carbon	1333-86-4	0.15%	0.01	1,460
	EMC GREEN	58.28%	3.44	silica	7631-86-9	43.11%	2.547	431,137
				epoxy resin	Proprietary	15.02%	0.883	150,205
				carbon	1333-86-4	0.15%	0.01	1,498
plating**	tin lead process	4.69%	0.28	Sn	7440-31-5	3.98%	0.23	39,830
				Pb	7439-92-1	0.70%	0.04	7,030
	100% tin process	4.69 %	0.28	Sn	7440-31-5	4.69%	0.28	46,860

*EMC GREEN molding compound is Halogen-Free.

**Specify Lead-Free when ordering 100% tin (Pb-free) plating.

Disclaimer

The information provided in this Material Composition data sheet is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.